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Requirements for Automated Inspection Process Control for Printed Board Assembly Processes

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Developed by the Automated Inspection for Printed Board Assemblies Process Control Standard Task Group (7-25a) of the Process Control Management Committee (7-20) of IPC

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A-Teams are dedicated groups of volunteers who undertake a significant amount of work in standards development on behalf of their working group.

IPC recognizes this A-Team for their exceptional leadership and effort in the development of this standard.

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